AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the above-identified application.

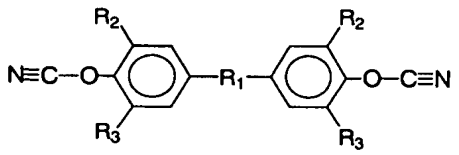
LISTING OF CLAIMS:

1. (Withdrawn) A resin composition for printed wiring board which comprises a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule.

2. (Withdrawn) The resin composition for printed wiring board according to Claim 1, wherein the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

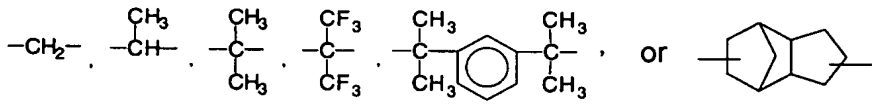
3. (Withdrawn) The resin composition for printed wiring board according to Claim 1, which further comprises a polyphenylene ether resin.

4. (Withdrawn) The resin composition for printed wiring board according to Claim 1, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one kind selected from the group consisting of a cyanate ester compound represented by the formula (I):



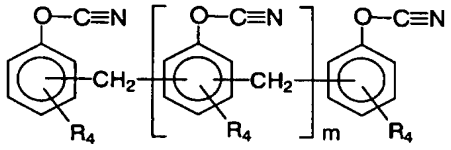
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

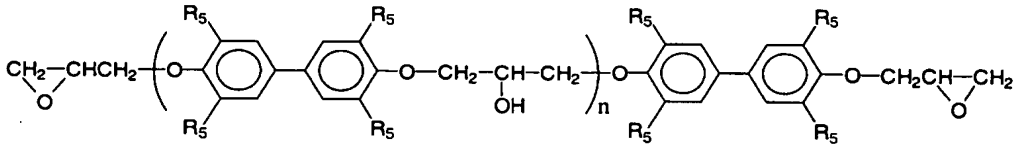


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

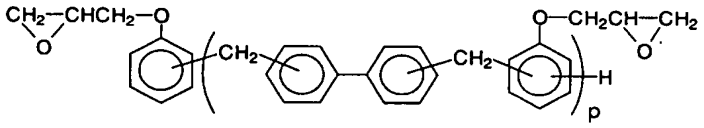
5. (Withdrawn) The resin composition for printed wiring board according to Claim 1, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



. . . . . Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

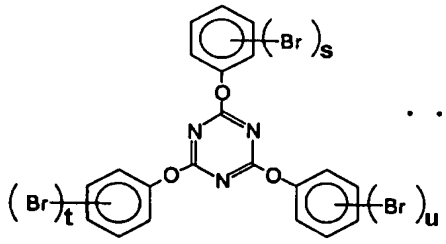
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

6. (Withdrawn) The resin composition for printed wiring board according to Claim 1, wherein the composition further comprises, ~~a~~ as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated poly-styrene.

7. (Withdrawn) The resin composition for printed wiring board according to Claim 1, which further comprises an antioxidant.

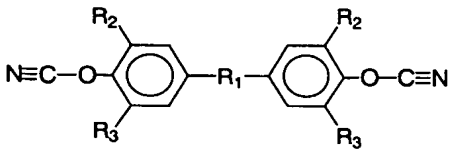
8. (Withdrawn) A resin composition for printed wiring board which comprises a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a

prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound.

9. (Withdrawn) The resin composition for printed wiring board according to Claim 8, wherein the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and the monovalent phenol compound is contained in an amount of 2 to 60 parts by weight based on the same.

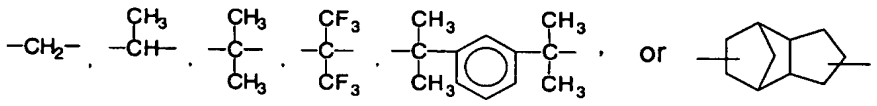
10. (Currently amended) A~~The~~ resin composition for printed wiring board which comprises a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound~~according to Claim 8~~, and which further comprises a polyphenylene ether resin.

11. (Withdrawn) The resin composition for printed wiring board according to Claim 8, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



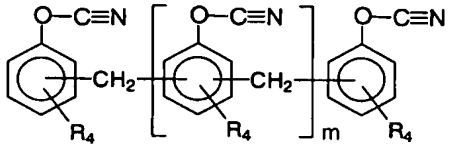
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

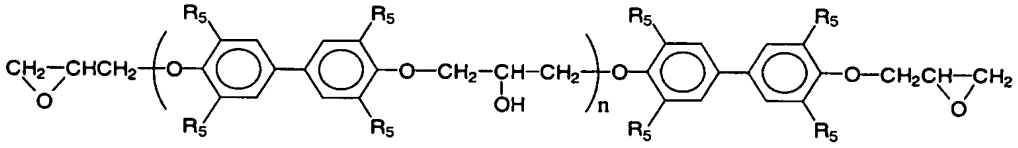


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

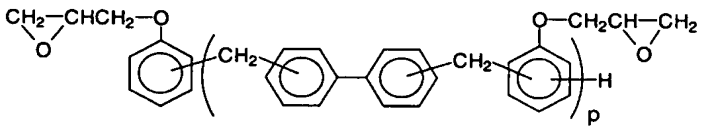
12. (Withdrawn) The resin composition for printed wiring board according to Claim 8, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



. . . . . Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

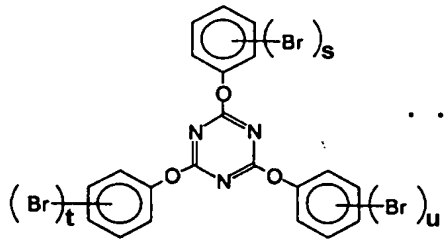
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

13. (Withdrawn) The resin composition for printed wiring board according to Claim 8, wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane , bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

14. (Withdrawn) The resin composition for printed wiring board according to Claim 8, which further comprises an antioxidant.

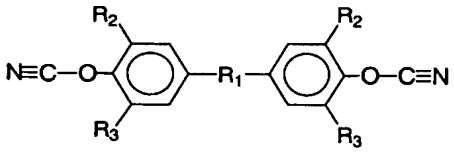
15. (Withdrawn) A resin composition for printed wiring board which comprises a phenol-modified cyanate ester oligomer obtained~~obtainable~~ by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a

prepolymer thereof, a monovalent phenol compound, and an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule.

16. (Withdrawn) The resin composition for printed wiring board according to Claim 15, wherein the phenol-modified cyanate ester oligomer is a phenol-modified cyanate ester oligomer obtained~~obtainable~~ by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof~~Component (A)~~ and 2 to 60 parts by weight of the monovalent phenol compound~~Component (C)~~, and the epoxy resin compound containing at least one kind of an epoxy resin having a biphenyl structure in the molecule~~Component (B)~~ is contained in an amount of 10 to 250 parts by weight.

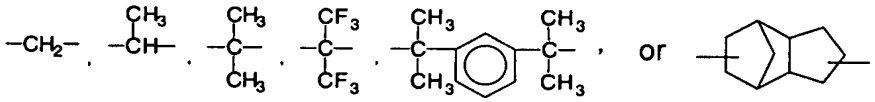
17. (Currently amended) A~~The~~ resin composition for printed wiring board which comprises a phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, a monovalent phenol compound, and an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule~~according to Claim 15~~, and which further comprises a poly-phenylene ether resin.

18. (Withdrawn) The resin composition for printed wiring board according to Claim 15, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



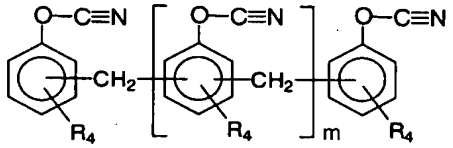
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

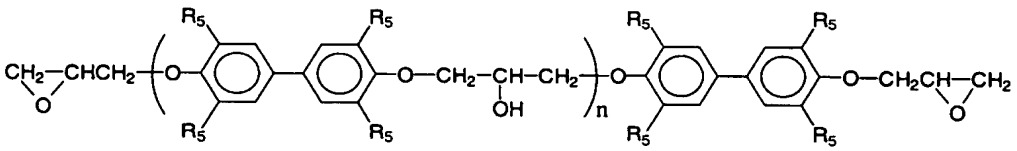


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

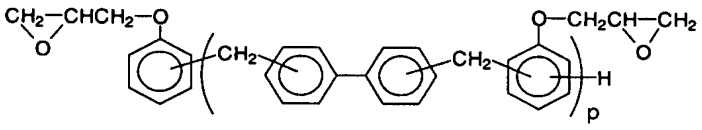
19. (Withdrawn) The resin composition for printed wiring board according to Claim 15, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

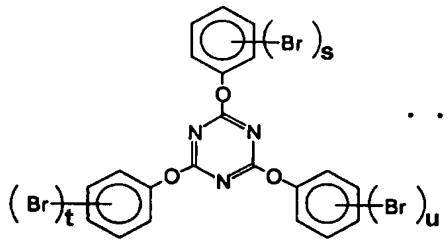
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

20. (Withdrawn) The resin composition for printed wiring board according to Claim 15, wherein the composition further comprises at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene, as a flame retardant.

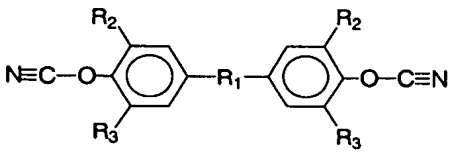
21. (Withdrawn) The resin composition for printed wiring board according to Claim 15, which further comprises an antioxidant.

22. (Withdrawn) A resin composition for printed wiring board which comprises a phenol-modified cyanate ester oligomer obtainable by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, a monovalent phenol compound, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound.

23. (Withdrawn) The resin composition for printed wiring board according to Claim 22, wherein the phenol-modified cyanate ester oligomer is a phenol-modified cyanate ester oligomer obtained~~obtainable~~ by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, 0.4 parts by weight or more and less than 60 parts by weight of the monovalent phenol compound, and the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight, and the monovalent phenol compound is additionally contained in a total amount of 2 to 60 parts by weight which is the sum of the amount with the monovalent phenol compound to be used for formation of the phenol-modified cyanate ester oligomer.

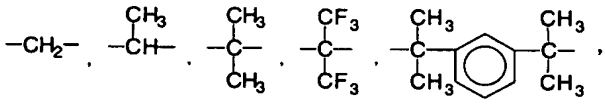
24. (Withdrawn) The resin composition for printed wiring board according to Claim 22, which further comprises a poly-phenylene ether.

25. (Withdrawn) The resin composition for printed wiring board according to Claim 22, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):

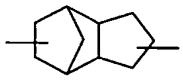


. . . . . Formula (I)

wherein R_1 represents

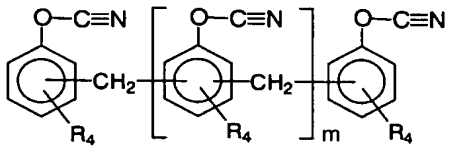


or



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):



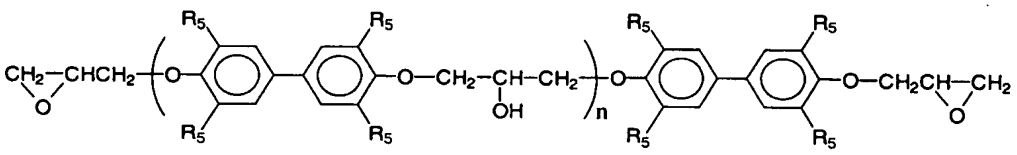
. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

26. (Withdrawn) The resin composition for printed wiring board according to Claim 22, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the

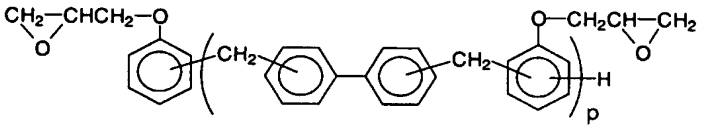
molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

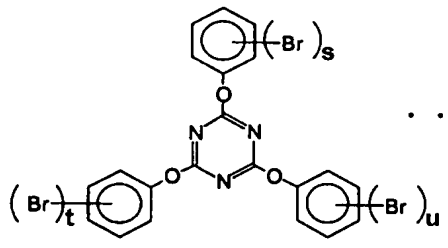
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

27. (Withdrawn) The resin composition for printed wiring board according to Claim 22, wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

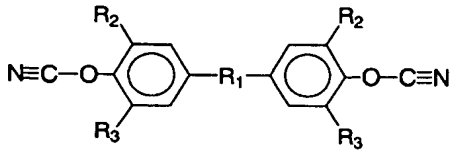
28. (Withdrawn) The resin composition for printed wiring board according to Claim 22, wherein the composition further comprises an antioxidant.

29. (Withdrawn) A resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound.

30. (Withdrawn) The resin composition for printed wiring board according to Claim 29, wherein the epoxy/phenol-modified cyanate ester oligomer is an epoxy/phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, 10 to 250 parts by weight of the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and 2 to 60 parts by weight of the monovalent phenol compound.

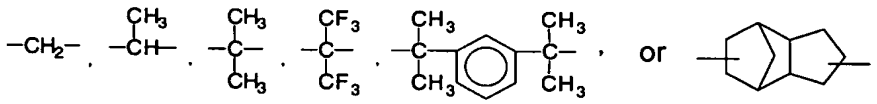
31. (Currently amended) A~~The~~ resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound~~according to Claim 29~~, and wherein the composition further comprises a polyphenylene ether resin.

32. (Withdrawn) The resin composition for printed wiring board according to Claim 29, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



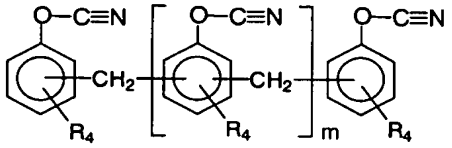
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):



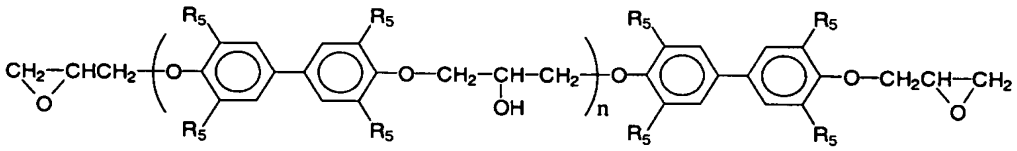
. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

33. (Withdrawn) The resin composition for printed wiring board according to Claim 29, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl

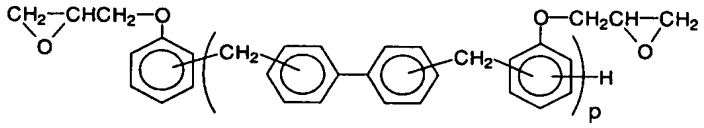
structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

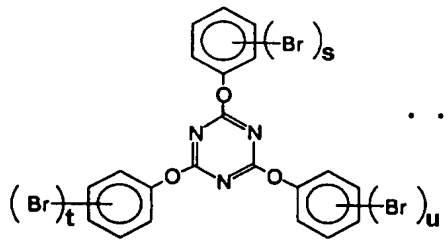
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

34. (Withdrawn) The resin composition for printed wiring board according to Claim 29, wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

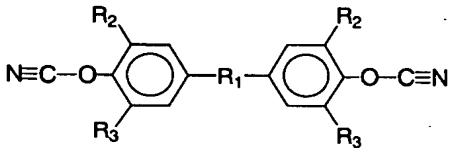
35. (Withdrawn) The resin composition for printed wiring board according to Claim 29, wherein the composition further comprises an antioxidant.

36. (Withdrawn) A resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and a monovalent phenol compound, and a monovalent phenol compound.

37. (Withdrawn) The resin composition for printed wiring board according to Claim 36, wherein the epoxy/phenol-modified cyanate ester oligomer is an epoxy/phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, 10 to 250 parts by weight of the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and 0.4 parts by weight or more and less than 60 parts by weight of the monovalent phenol compound, and the monovalent phenol compound is additionally contained in a total amount of 2 to 60 parts by weight which is the sum of the amount with the monovalent phenol compound to be used for formation of the epoxy/phenol-modified cyanate ester oligomer.

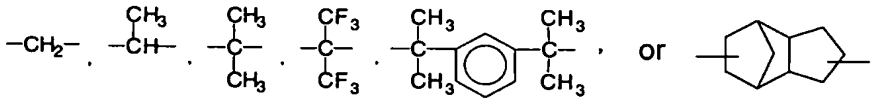
38. (Withdrawn) The resin composition for printed wiring board according to Claim 36, wherein the composition further comprises a polyphenylene ether resin.

39. (Withdrawn) The resin composition for printed wiring board according Claim 36, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



. . . . . Formula (I)

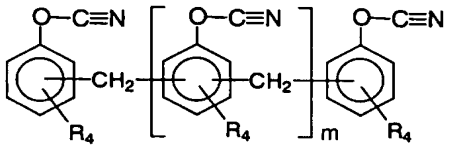
wherein R_1 represents



or

R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):



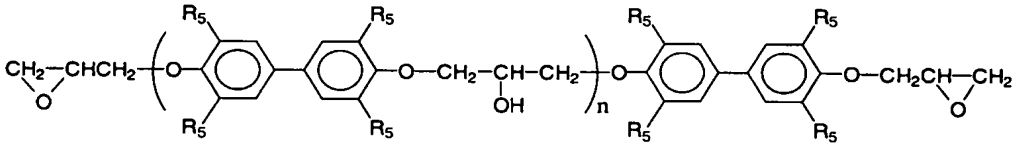
. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

40. (Withdrawn) The resin composition for printed wiring board according to Claim 36, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the

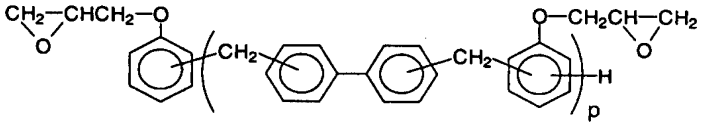
molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

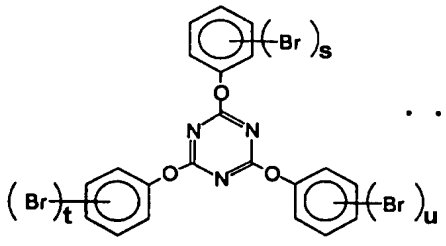
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

41. (Withdrawn) The resin composition for printed wiring board according to Claim 36, wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

42. (Withdrawn) The resin composition for printed wiring board according to Claim 36, wherein the composition further comprises an antioxidant.

43. (Withdrawn) A resin composition for printed wiring board which comprises a phenol-modified cyanate ester oligomer which is obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and a monovalent phenol compound in the presence of a polyphenylene ether resin.

44. (Original) A resin composition for printed wiring board which comprises an epoxy/phenol-modified cyanate ester oligomer obtained by reacting a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, a monovalent phenol compound and an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule in the presence of a polyphenylene ether resin.

45. (Withdrawn) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 1 in a solvent.

46. (Withdrawn) A prepreg for a printed wiring board which is obtained by impregnating the resin composition for printed wiring board according to Claim 1 into a substrate, and drying at 80 to 200°C.

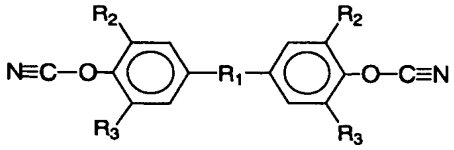
47. (Withdrawn) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 46, laminating a metal foil on at least one surface thereof and pressurizing under heating.

48. (Withdrawn) A prepreg for a printed wiring board which is obtained by impregnating the resin varnish for a printed wiring board according to Claim 45 into a substrate, and drying at 80 to 200°C.

49. (Withdrawn) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 48, laminating a metal foil on at least one surface thereof and pressurizing under heating.

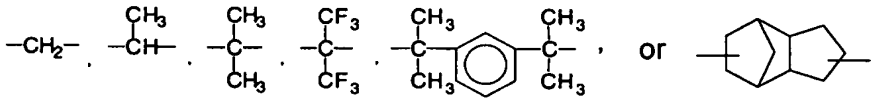
50. (New) The resin composition for printed wiring board according to Claim 10, wherein the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and the monovalent phenol compound is contained in an amount of 2 to 60 parts by weight based on 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof.

51. (New) The resin composition for printed wiring board according to Claim 10, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



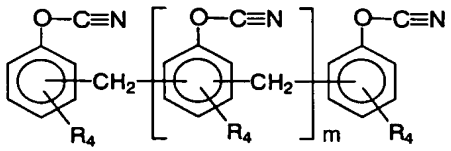
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

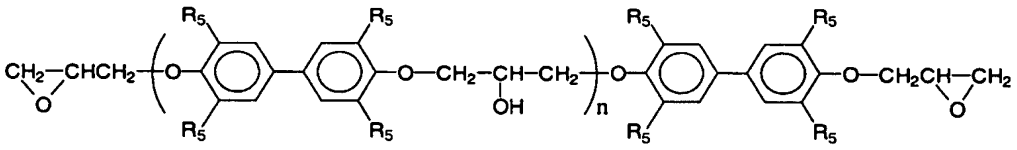


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

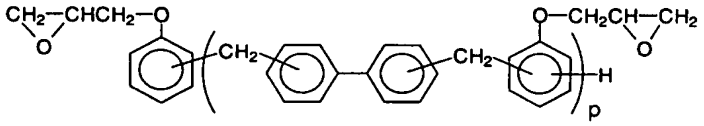
52. (New) The resin composition for printed wiring board according to Claim 10, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

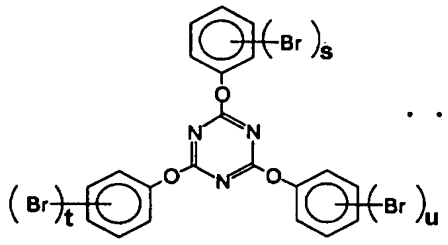
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

53. (New) The resin composition for printed wiring board according to Claim 10 , wherein the composition further comprises, as a flame retardant, at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane , bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene.

54. (New) The resin composition for printed wiring board according to Claim 10, which further comprises an antioxidant.

55. (New) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 10 in a solvent.

56. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin composition for printed wiring board according to Claim 10 into a substrate, and drying at 80 to 200°C.

57. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 56, laminating a metal foil on at least one surface thereof and pressurizing under heating.

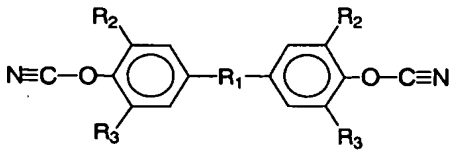
58. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin varnish for a printed wiring board according to Claim 55 into a substrate, and drying at 80 to 200°C.

59. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 58, laminating a metal foil on at least one surface thereof and pressurizing under heating.

60. (New) The resin composition for printed wiring board according to Claim 17, wherein the phenol-modified cyanate ester oligomer is a phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester

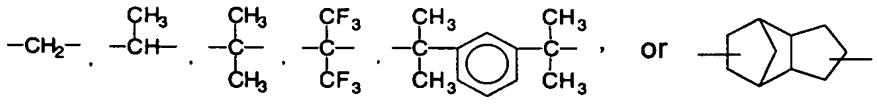
compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, and 2 to 60 parts by weight of the monovalent phenol compound, and the epoxy resin compound containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is contained in an amount of 10 to 250 parts by weight.

61. (New) The resin composition for printed wiring board according to Claim 17, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



. . . . . Formula (I)

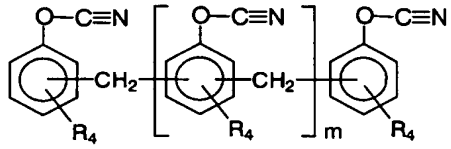
wherein R_1 represents



or

R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

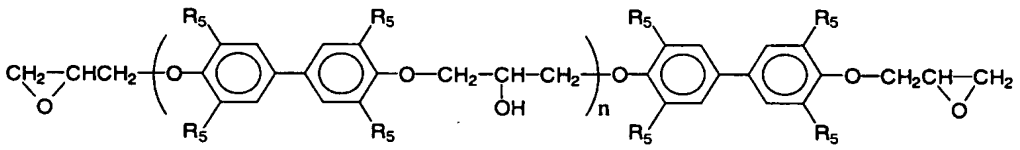


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

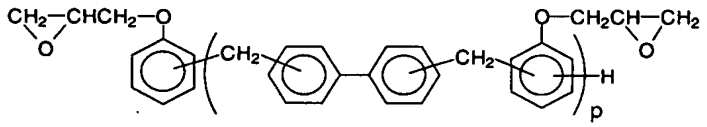
62. (New) The resin composition for printed wiring board according to Claim 17, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



· · · · · Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

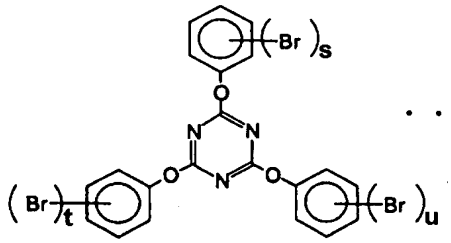
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

63. (New) The resin composition for printed wiring board according to Claim 17, wherein the composition further comprises at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,

a brominated polyphenylene ether and a brominated polystyrene, as a flame retardant.

64. (New) The resin composition for printed wiring board according to Claim 17, which further comprises an antioxidant.

65. (New) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 17 in a solvent.

66. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin composition for printed wiring board according to Claim 17 into a substrate, and drying at 80 to 200°C.

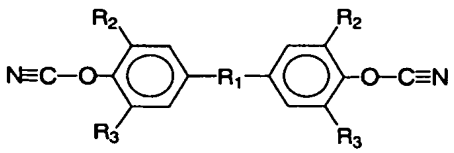
67. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 66, laminating a metal foil on at least one surface thereof and pressurizing under heating.

68. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin varnish for a printed wiring board according to Claim 65 into a substrate, and drying at 80 to 200°C.

69. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 68, laminating a metal foil on at least one surface thereof and pressurizing under heating.

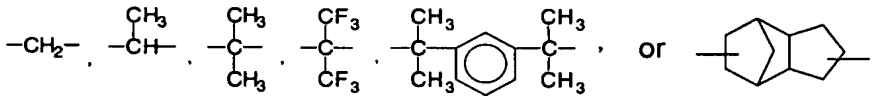
70. (New) The resin composition for printed wiring board according to Claim 31, wherein the epoxy/phenol-modified cyanate ester oligomer is an epoxy/phenol-modified cyanate ester oligomer obtained by reacting 100 parts by weight of the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof, 10 to 250 parts by weight of the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule, and 2 to 60 parts by weight of the monovalent phenol compound.

71. (New) The resin composition for printed wiring board according to Claim 31, wherein the cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is at least one selected from the group consisting of a cyanate ester compound represented by the formula (I):



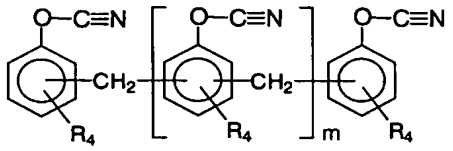
. . . . . Formula (I)

wherein R_1 represents



R_2 and R_3 each represent a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, and each may be the same or different from each other,

and a cyanate ester compound represented by the formula (II):

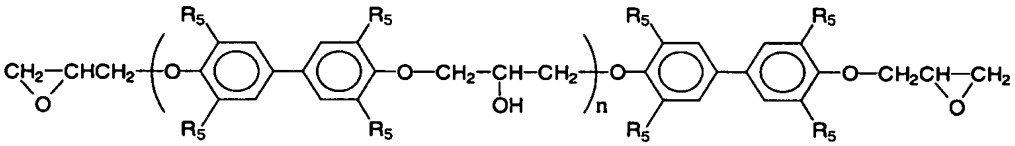


. . . . . Formula (II)

wherein R_4 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms, m represents an integer of 1 to 7,

and a prepolymer thereof.

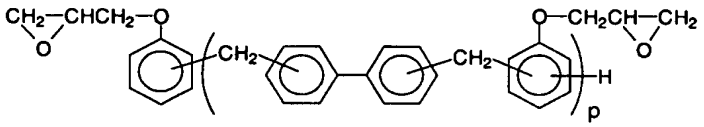
72. (New) The resin composition for printed wiring board according to Claim 31, wherein the epoxy resin having a biphenyl structure in the molecule in the epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is at least one selected from the group consisting of an epoxy resin represented by the formula (III):



. . . . . Formula (III)

wherein R_5 each represent a hydrogen atom or a methyl group, n represents an integer of 0 to 6,

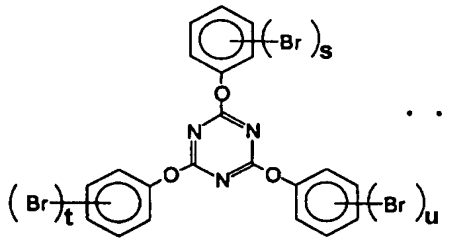
and an epoxy resin represented by the formula (IV):



· · · · · Formula (IV)

wherein p represents an integer of 1 to 5.

73. (New) The resin composition for printed wiring board according to Claim 31, wherein the composition further comprises at least one selected from the group consisting of 1,2-dibromo-4-(1,2-dibromoethyl)cyclohexane, tetrabromocyclooctane, hexabromocyclododecane, bis(tribromophenoxy)ethane, a brominated triphenylcyanurate represented by the formula (VII):



· · · · · Formula (VII)

wherein s, t and u each represent an integer of 1 to 5, and each may by the same value or different from each other,
a brominated polyphenylene ether and a brominated polystyrene, as a flame retardant.

74. (New) The resin composition for printed wiring board according to Claim 31, which further comprises an antioxidant.

75. (New) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 31 in a solvent.

76. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin composition for printed wiring board according to Claim 31 into a substrate, and drying at 80 to 200°C.

77. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 76, laminating a metal foil on at least one surface thereof and pressurizing under heating.

78. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin varnish for a printed wiring board according to Claim 75 into a substrate, and drying at 80 to 200°C.

79. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 78, laminating a metal foil on at least one surface thereof and pressurizing under heating.

80. (New) A resin varnish for a printed wiring board obtained by dissolving or dispersing the resin composition for printed wiring board according to Claim 44 in a solvent.

81. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin composition for printed wiring board according to Claim 44 into a substrate, and drying at 80 to 200°C.

82. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 81, laminating a metal foil on at least one surface thereof and pressurizing under heating.

83. (New) A prepreg for a printed wiring board which is obtained by impregnating the resin varnish for a printed wiring board according to Claim 80 into a substrate, and drying at 80 to 200°C.

84. (New) A metal clad laminated board which is obtained by laminating one or more of the prepreg for a printed wiring board according to Claim 83, laminating a metal foil on at least one surface thereof and pressurizing under heating.